



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: **Kozo SHIMIZU et al.**

Group Art Unit: 1742

Serial No.: 09/731,726

Examiner: **Sikyin Ip**

Filed: **December 8, 2000**

P.T.O. Confirmation No.: 1555

FOR: **A SOLDER ALLOY, A CIRCUIT SUBSTRATE, A SEMICONDUCTOR DEVICE
AND A METHOD OF MANUFACTURING THE SAME**

AMENDMENT UNDER 37 C.F.R. §1.111

Commissioner for Patents
Washington, D.C. 20231

June 26, 2002

Sir:

In response to the Office Action dated **March 27, 2002**, please amend the above identified application as follows:

CLEAN VERSION OF AMENDMENTS

IN THE CLAIMS

Please add new claims 15 and 16 as follows:

15. (New) The semiconductor device of claim 1, said solder alloy being made from Sn prepared using a zone-melt method.

16. (New) The circuit substrate of claim 4, said solder alloy being made from Sn prepared using a zone-melt method.

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